



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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BOARD LEVEL COOLING - 3358

3358 is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. These heat sinks use pressure sensitive adhesive for mounting. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
335824B00032G	BGA, FPGA
335824B00034G	BGA, FPGA

HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Tape
Thermal Interface Material 335824B00032G	T405R Chomerics Tape for Metal Surfaces
Thermal Interface Material 335824B00034G	T410R Chomerics Tape for Plastic Surfaces

Property	Details
Heat Sink Width (mm)	29.97
Heat Sink Length (mm)	29.97
Heat Sink Height (mm)	9.40
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

